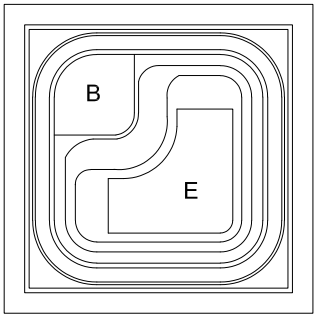
CP388X-BC847B
NPN - Low Noise Transistor Die

www.centralsemi.com

The CP388X-BC847B is a silicon NPN transistor designed for low noise amplifier applications.



BACKSIDE COLLECTOR R0

MECHANICAL SPECIFICATIONS:

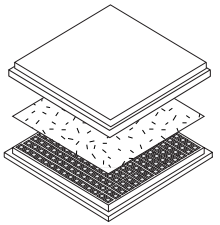
Die Size	13 x 13 MILS
Die Thickness	5.9 MILS
Base Bonding Pad Size	3.9 x 3.9 MILS
Emitter Bonding Pad Size	5.4 x 5.4 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	1.8 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	102,852

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**	**BC847**	**UNITS**
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	6.0	V
Continuous Collector Current	I_C	100	mA
Peak Collector Current	I_{CM}	200	mA
Peak Base Current	I_{BM}	200	mA
Operating and Storage Junction Temperature	T_J, T_{stg}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	**TEST CONDITIONS**	**MIN**	**TYP**	**MAX**	**UNITS**
I_{CBO}	V_{CB}=30V			15	nA
I_{EBO}	V_{EB}=5.0V			100	nA
BV_{CBO}	I_C=10μA	50			V
BV_{CEO}	I_C=10mA	45			V
BV_{EBO}	I_E=10μA	6.0			V
$V_{CE(SAT)}$	I_C=10mA, I_B=0.5mA			0.25	V
$V_{CE(SAT)}$	I_C=100mA, I_B=5.0mA			0.60	V
$V_{BE(SAT)}$	I_C=10mA, I_B=0.5mA		0.70		V
$V_{BE(SAT)}$	I_C=100mA, I_B=5.0mA		0.90		V
$V_{BE(ON)}$	I_C=2.0mA, V_{CE}=5.0V	0.58		0.70	V
$V_{BE(ON)}$	I_C=10mA, V_{CE}=5.0V			0.77	V
h_{FE}	V_{CE}=5.0V, I_C=2.0mA	200		450	
C_{cb}	V_{CB}=10V, I_E=0, f=1.0MHz			4.5	pF

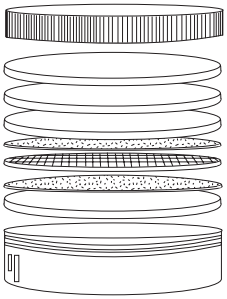
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

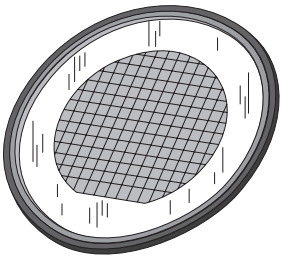
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



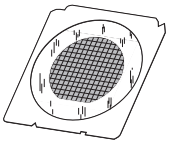
UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)



Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.

Visit the Central website for a complete listing of specifications:
www.centralsemi.com/bdspecs

R2 (3-April 2017)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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